

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2977659

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
WENJUN LI	06/30/2014
JUN HU	06/27/2014
HUANG LOU	06/27/2014
VANSH PAL SINGH MAKH	07/24/2014
FRANCIS MING-MENG NGAI	07/24/2014
ASHISH GAONEKAR	07/01/2014
VARSHA RAO	08/06/2014
SUREKHA MURALIDHARAN	07/30/2014
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14307577
CORRESPONDENCE DATA	
Fax Number:	(703)391-2901
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	7033912900
Email:	ptonoticesqc@marburylaw.com
Correspondent Name:	THE MARBURY LAW GROUP, PLLC
Address Line 1:	11800 SUNRISE VALLEY DRIVE
Address Line 2:	15TH FLOOR
Address Line 4:	RESTON, VIRGINIA 20191
ATTORNEY DOCKET NUMBER:	141019 / 1376-1376
NAME OF SUBMITTER:	ROBERT M. HANSEN
SIGNATURE:	/Robert M. Hansen/

PATENT

DATE SIGNED:	08/12/2014
Total Attachments: 24 source=141019_Assignment_Filed#page1.tif source=141019_Assignment_Filed#page2.tif source=141019_Assignment_Filed#page3.tif source=141019_Assignment_Filed#page4.tif source=141019_Assignment_Filed#page5.tif source=141019_Assignment_Filed#page6.tif source=141019_Assignment_Filed#page7.tif source=141019_Assignment_Filed#page8.tif source=141019_Assignment_Filed#page9.tif source=141019_Assignment_Filed#page10.tif source=141019_Assignment_Filed#page11.tif source=141019_Assignment_Filed#page12.tif source=141019_Assignment_Filed#page13.tif source=141019_Assignment_Filed#page14.tif source=141019_Assignment_Filed#page15.tif source=141019_Assignment_Filed#page16.tif source=141019_Assignment_Filed#page17.tif source=141019_Assignment_Filed#page18.tif source=141019_Assignment_Filed#page19.tif source=141019_Assignment_Filed#page20.tif source=141019_Assignment_Filed#page21.tif source=141019_Assignment_Filed#page22.tif source=141019_Assignment_Filed#page23.tif source=141019_Assignment_Filed#page24.tif	

ASSIGNMENT

WHEREAS, WE,

1. **Wenjun LI**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
2. **Jun HU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
3. **Huang LOU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
4. **Vansh Pal Singh MAKH**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Francisco, CA;
5. **Francis Ming-Meng NGAI**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Louisville, CO;
6. **Ashish GAONEKAR**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Hyderabad, IN;
7. **Varsha RAO**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA; and
8. **Surekha MURALIDHARAN**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Pleasanton, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to OPPORTUNISTIC MOBILE RECEIVE DIVERSITY (OMRD) IN A DUAL-SIM DUAL-ACTIVE (DSDA) DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/307,577 filed June 18, 2014, Qualcomm Reference No. 141019 and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/973,001, filed March 31, 2014, Qualcomm Reference No. 141019P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

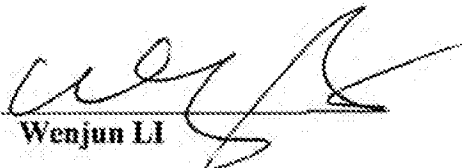
AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, on 6/30/2014
LOCATION DATE

Wenjun LI

Done at _____, on _____
LOCATION DATE
Jun HU

Done at _____, on _____
LOCATION DATE
Huang LOU

Done at _____, on _____
LOCATION DATE
Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE
Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE
Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE
Varsha RAO

Done at _____, on _____
LOCATION DATE
Surekha MURALIDHARAN

ASSIGNMENT

WHEREAS, WE,

1. **Wenjun LI**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/307,577 filed June 18, 2014, Qualcomm Reference No. 141019 and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/973,001, filed March 31, 2014, Qualcomm Reference No. 141019P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE

Wenjun LI

Done at San Diego, CA, USA, on 6/27/2014
LOCATION DATE

Jun HU

Done at _____, on _____
LOCATION DATE

Huang LOU

Done at _____, on _____
LOCATION DATE

Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE

Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE

Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE

Varsha RAO

Done at _____, on _____
LOCATION DATE

Surekha MURALIDHARAN

ASSIGNMENT

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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/307,577 filed June 18, 2014, Qualcomm Reference No. 141019 and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/973,001, filed March 31, 2014, Qualcomm Reference No. 141019P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Wenjun LI

Done at _____, on _____
LOCATION DATE Jun HU

Done at San Diego, CA, on 06/27/2014
LOCATION DATE Huang LOU

Done at _____, on _____
LOCATION DATE Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE Varsha RAO

Done at _____, on _____
LOCATION DATE Surekha MURALIDHARAN

ASSIGNMENT

WHEREAS, WE,

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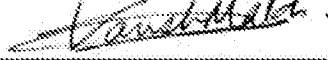
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Done at _____, on _____
LOCATION DATE Wenjun LI

Done at _____, on _____
LOCATION DATE Jun HU

Done at _____, on _____
LOCATION DATE Huang LOU

Done at SANTA CLARA, on 7/24/14
LOCATION DATE 
Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE Varsha RAO

Done at _____, on _____
LOCATION DATE Surekha MURALIDHARAN

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WHEREAS, WE,

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8. **Surekha MURALIDHARAN**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Pleasanton, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to OPPORTUNISTIC MOBILE RECEIVE DIVERSITY (OMRD) IN A DUAL-SIM DUAL-ACTIVE (DSDA) DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/307,577 filed June 18, 2014, Qualcomm Reference No. 141019 and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/973,001, filed March 31, 2014, Qualcomm Reference No. 141019P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Wenjun LI

Done at _____, on _____
LOCATION DATE Jun HU

Done at _____, on _____
LOCATION DATE Huang LOU

Done at _____, on _____
LOCATION DATE Vansh Pal Singh MAKH

Done at ^{BOULDER,} COLORADO, on JULY 24, 2014
LOCATION DATE Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE Varsha RAO

Done at _____, on _____
LOCATION DATE Surekha MURALIDHARAN

ASSIGNMENT

WHEREAS, WE,

1. **Wenjun LI**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
2. **Jun HU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
3. **Huang LOU**, a citizen of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA;
4. **Vansh Pal Singh MAKH**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Francisco, CA;
5. **Francis Ming-Meng NGAI**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Louisville, CO;
6. **Ashish GAONEKAR**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Hyderabad, IN;
7. **Varsha RAO**, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of San Diego, CA; and
8. **Surekha MURALIDHARAN**, a citizen of the United States, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121-1714, and a resident of Pleasanton, CA;

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to OPPORTUNISTIC MOBILE RECEIVE DIVERSITY (OMRD) IN A DUAL-SIM DUAL-ACTIVE (DSDA) DEVICE (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest

throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 14/307,577 filed June 18, 2014, Qualcomm Reference No. 141019 and all provisional applications relating thereto, together with U.S. Provisional Application No(s). 61/973,001, filed March 31, 2014, Qualcomm Reference No. 141019P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

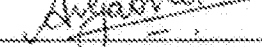
Done at _____, on _____
LOCATION DATE Wenjun LI

Done at _____, on _____
LOCATION DATE Jun HU

Done at _____, on _____
LOCATION DATE Huang LOU

Done at _____, on _____
LOCATION DATE Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE Francis Ming-Meng NGAI

Done at Hyderabad, TN, on 07/01/2014
LOCATION DATE 
Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE Varsha RAO

Done at _____, on _____
LOCATION DATE Surekha MURALIDHARAN

ASSIGNMENT

WHEREAS, WE,

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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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Done at _____, on _____
LOCATION DATE Wenjun LI

Done at _____, on _____
LOCATION DATE Jun HU

Done at _____, on _____
LOCATION DATE Huang LOU

Done at _____, on _____
LOCATION DATE Vansh Pal Singh MAKH

Done at _____, on _____
LOCATION DATE Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE Ashish GAONEKAR

Done at San Diego, CA, on 08/06/14
LOCATION DATE *Varsha Rao*
Varsha RAO

Done at _____, on _____
LOCATION DATE Surekha MURALIDHARAN

ASSIGNMENT

WHEREAS, WE,

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LOCATION DATE Francis Ming-Meng NGAI

Done at _____, on _____
LOCATION DATE Ashish GAONEKAR

Done at _____, on _____
LOCATION DATE Varsha RAO

Done at San Diego, CA, on 07/30/2014
LOCATION DATE 
Surekha MURALIDHARAN